Hex Non-Inverting 3-State Buffer

The MC14503B is a hex non-inverting buffer with 3-state outputs, and a high current source and sink capability. The 3-state outputs make it useful in common bussing applications. Two disable controls are provided. A high level on the Disable A input causes the outputs of buffers 1 through 4 to go into a high impedance state and a high level on the Disable B input causes the outputs of buffers 5 and 6 to go into a high impedance state.

- 3-State Outputs
- TTL Compatible Will Drive One TTL Load Over Full Temperature Range
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Two Disable Controls for Added Versatility
- Pin for Pin Replacement for MM80C97 and 340097
- These devices are available in Pb-free package(s). Specifications herein apply to both standard and Pb-free devices. Please see our website at www.onsemi.com for specific Pb-free orderable part numbers, or contact your local ON Semiconductor sales office or representative.

MAXIMUM RATINGS (Voltages Referenced to V_{SS}) (Note 1.)

Symbol	Parameter	Value	Unit
V_{DD}	DC Supply Voltage Range	-0.5 to +18.0	V
V _{in} , V _{out}	Input or Output Voltage Range (DC or Transient)	-0.5 to V _{DD} + 0.5	>
l _{in}	Input Current (DC or Transient) per Pin	±10	mA
l _{out}	Output Current (DC or Transient) per Pin	±25	mA
P _D	Power Dissipation, per Package (Note 2.)	500	mW
T _A	Ambient Temperature Range	-55 to +125	°C
T _{stg}	Storage Temperature Range	-65 to +150	°C
TL	Lead Temperature (8-Second Soldering)	260	°C

- Maximum Ratings are those values beyond which damage to the device may occur.
- Temperature Derating: Plastic "P and D/DW" Packages: – 7.0 mW/°C From 65°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}.$

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.

1



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MARKING DIAGRAMS



PDIP-16 P SUFFIX CASE 648



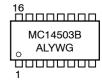


SOIC-16 D SUFFIX CASE 751B





SOEIAJ-16 F SUFFIX CASE 966



= Assembly Location

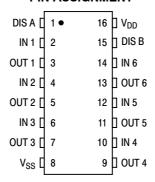
WL, L = Wafer Lot YY, Y = Year WW, W = Work Week G = Pb-Free Indicator

ORDERING INFORMATION

Device	Package	Shipping	
MC14503BCP	PDIP-16	2000/Box	
MC14503BD	SOIC-16	48/Rail	
MC14503BDR2	SOIC-16	2500/Tape & Reel	
MC14503BF	SOEIAJ-16	See Note 1.	
MC14503BFEL	SOEIAJ-16	See Note 1.	

 For ordering information on the EIAJ version of the SOIC packages, please contact your local ON Semiconductor representative.

PIN ASSIGNMENT

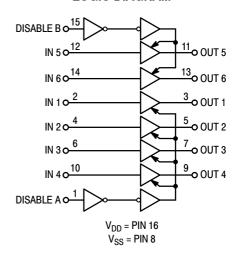


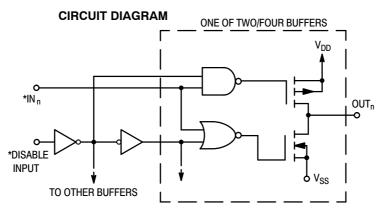
TRUTH TABLE

In _n	Appropriate Disable Input	Out _n
0	0	0
1	0	1
X	1	High Impedance

X = Don't Care

LOGIC DIAGRAM





*Diode protection on all inputs (not shown)

ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

			V_{DD}	- 5	5°C		25°C		125	5°C	
Characteristic		Symbol	Vdc	Min	Max	Min	Typ ^(3.)	Max	Min	Max	Unit
Output Voltage V _{in} = 0	"0" Level	V _{OL}	5.0 10 15	_ _ _	0.05 0.05 0.05	_ _ _	0 0 0	0.05 0.05 0.05	_ _ _	0.05 0.05 0.05	Vdc
$V_{in} = V_{DD}$	"1" Level	V _{OH}	5.0 10 15	4.95 9.95 14.95	_ _ _	4.95 9.95 14.95	5.0 10 15	_ _ _	4.95 9.95 14.95	_ _ _	Vdc
Input Voltage (V _O = 3.6 or 1.4 Vdc) (V _O = 7.2 or 2.8 Vdc) (V _O = 11.5 or 3.5 Vdc)	"0" Level	V _{IL}	5.0 10 15		1.5 3.0 4.0	_ _ _	2.25 4.50 6.75	1.5 3.0 4.0		1.5 3.0 4.0	Vdc
$(V_O = 1.4 \text{ or } 3.6 \text{ Vdc})$ $(V_O = 2.8 \text{ or } 7.2 \text{ Vdc})$ $(V_O = 3.5 \text{ or } 11.5 \text{ Vdc})$	"1" Level	V _{IH}	5.0 10 15	3.5 7.0 11	_ _ _	3.5 7.0 11	2.75 5.50 8.25	_ _ _	3.5 7.0 11	_ _ _	Vdc
Output Drive Current	Source	I _{OH}	4.5 5.0 5.0 10 15	- 4.3 - 5.8 - 1.2 - 3.1 - 8.2	 	- 3.6 - 4.8 - 1.02 - 2.6 - 6.8	- 5.0 - 6.1 - 1.4 - 3.7 - 14.1	 	- 2.5 - 3.0 - 0.7 - 1.8 - 4.8	_ _ _ _	mAdc
$(V_{OL} = 0.4 \text{ Vdc})$ $(V_{OL} = 0.4 \text{ Vdc})$ $(V_{OL} = 0.5 \text{ Vdc})$ $(V_{OL} = 1.5 \text{ Vdc})$	Sink	I _{OL}	4.5 5.0 10 15	2.2 2.6 6.5 19.2	— — — —	1.8 2.1 5.5 16.1	2.1 2.3 6.2 25	— — — —	1.2 1.3 3.8 11.2		mAdc
Input Current		I _{in}	15	_	± 0.1	_	±0.00001	± 0.1	_	± 1.0	μAdc
Input Capacitance (V _{in} = 0)		C _{in}	_	_	_	_	5.0	7.5	_	_	pF
Quiescent Current (Per Package)		IQ	5.0 10 15	_ _ _	1.0 2.0 4.0	_ _ _	0.002 0.004 0.006	1.0 2.0 4.0	_ _ _	30 60 120	μAdc
Total Supply Current ^(4.) ^(5.) (Dynamic plus Quiesce Per Package) (C _L = 50 pF on all output (All outputs switching, 50% Duty Cycle)	ent,	I _T	5.0 10 15			$I_T = (6$	2.5 μΑ/kHz) f 6.0 μΑ/kHz) f 10 μΑ/kHz) f	+ I _{DD}			μAdc
Three-State Output Leaka Current	ge	I _{TL}	15	_	± 0.1	_	± 0.0001	± 0.1	_	± 3.0	μAdc

Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
 The formulas given are for the typical characteristics only at 25°C.
 To calculate total supply current at loads other than 50 pF:

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$$

where: I_T is in μA (per package), C_L in pF, $V = (V_{DD} - V_{SS})$ in volts, f in kHz is input frequency, and k = 0.006.

SWITCHING CHARACTERISTICS ^(6.) (C_L = 50 pF, T_A = 25°C)

		V _{DD}	All T	ypes	
Characteristic	Symbol	V _{CC}	Typ ^(7.)	Max	Unit
Output Rise Time $t_{TLH} = (0.5 \text{ ns/pF}) C_L + 20 \text{ ns}$ $t_{TLH} = (0.3 \text{ ns/pF}) C_L + 8.0 \text{ ns}$ $t_{TLH} = (0.2 \text{ ns/pF}) C_L + 8.0 \text{ ns}$	t _{TLH}	5.0 10 15	45 23 18	90 45 35	ns
Output Fall Time $t_{THL} = (0.5 \text{ ns/pF}) C_L + 20 \text{ ns}$ $t_{THL} = (0.3 \text{ ns/pF}) C_L + 8.0 \text{ ns}$ $t_{THL} = (0.2 \text{ ns/pF}) C_L + 8.0 \text{ ns}$	t _{THL}	5.0 10 15	45 23 18	90 45 35	ns
Turn-Off Delay Time, all Outputs $t_{PLH} = (0.3 \text{ ns/pF}) C_L + 60 \text{ ns}$ $t_{PLH} = (0.15 \text{ ns/pF}) C_L + 27 \text{ ns}$ $t_{PLH} = (0.1 \text{ ns/pF}) C_L + 20 \text{ ns}$	t _{PLH}	5.0 10 15	75 35 25	150 70 50	ns
Turn–On Delay Time, all Outputs $t_{PHL} = (0.3 \text{ ns/pF}) \text{ C}_{L} + 60 \text{ ns}$ $t_{PHL} = (0.15 \text{ ns/pF}) \text{ C}_{L} + 27 \text{ ns}$ $t_{PHL} = (0.1 \text{ ns/pF}) \text{ C}_{L} + 20 \text{ ns}$	t _{PHL}	5.0 10 15	75 35 25	150 70 50	ns
3–State Propagation Delay Time Output "1" to High Impedance	t _{РНZ}	5.0 10 15	75 40 35	150 80 70	ns
Output "0" to High Impedance	t _{PLZ}	5.0 10 15	80 40 35	160 80 70	ns
High Impedance to "1" Level	t _{PZH}	5.0 10 15	65 25 20	130 50 40	ns
High Impedance to "0" Level	† _{PZL}	5.0 10 15	100 35 25	200 70 50	ns

- 6. The formulas given are for the typical characteristics only at 25°C.
 7. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

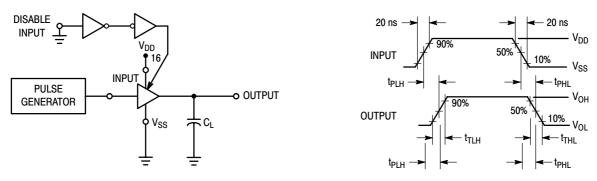
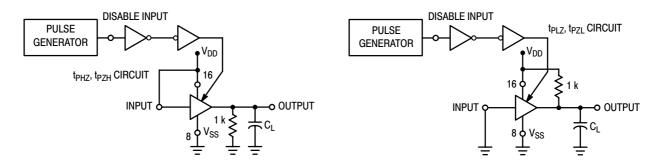


Figure 1. Switching Time Test Circuit and Waveforms (t_{TLH}, t_{THL}, t_{PHL}, and t_{PLH})



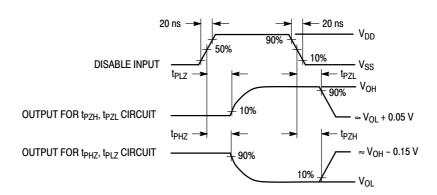
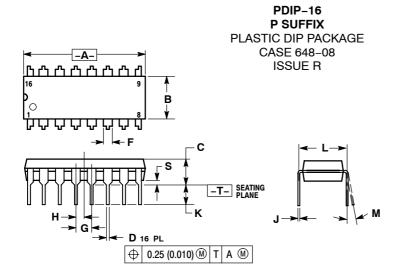


Figure 2. 3–State AC Test Circuit and Waveforms $(t_{PLZ},\,t_{PHZ},\,t_{PZH},\,t_{PZL})$

PACKAGE DIMENSIONS



NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: INCH.

 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.

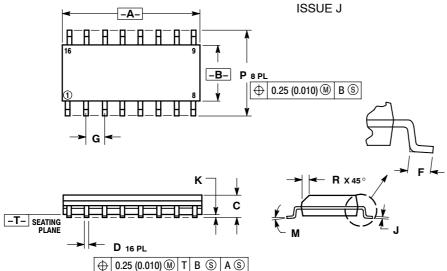
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

 5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIN	ETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
С	0.145	0.175	3.69	4.44	
D	0.015	0.021	0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100	BSC	2.54 BSC		
Н	0.050	BSC	1.27 BSC		
J	0.008	0.015	0.21	0.38	
K	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
M	0°	10 °	0°	10 °	
S	0.020	0.040	0.51	1.01	

SOIC-16 **D SUFFIX**

PLASTIC SOIC PACKAGE CASE 751B-05



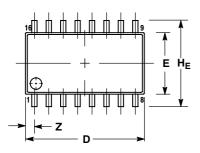
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) DED SIDE
- MAXIMUM MOLD PROTROSION 0.15 (0.000)
 PER SIDE.
 DIMENSION D DOES NOT INCLUDE DAMBAR
 PROTRUSION. ALLOWABLE DAMBAR
 PROTRUSION SHALL BE 0.127 (0.005) TOTAL
 IN EXCESS OF THE D DIMENSION AT
 MAXIMUM MATERIAL CONDITION.

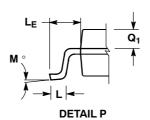
	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	9.80	10.00	0.386	0.393
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050	BSC
7	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
Р	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

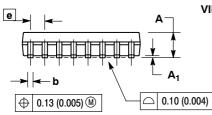
PACKAGE DIMENSIONS

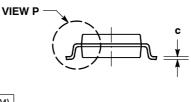
SOEIAJ-16 **F SUFFIX**

PLASTIC EIAJ SOIC PACKAGE CASE 966-01 ISSUE O









NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIN	IILLIMETERS INCHES		
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
С	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
е	1.27	BSC	0.050	BSC
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10 °
Q_1	0.70	0.90	0.028	0.035
Z		0.78		0.031

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